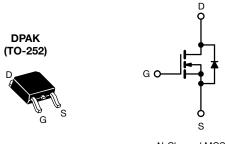
Vishay Siliconix



E Series Power MOSFET



PRODUCT SUMMARY				
V_{DS} (V) at T_{J} max.	850			
R _{DS(on)} typ. (Ω) at 25 °C	$V_{GS} = 10 V$	2.38		
Q _g max. (nC)	90			
Q _{gs} (nC)	11			
Q _{gd} (nC)	19			
Configuration	Single			

FEATURES

- Low figure-of-merit (FOM) Ron x Qg
- Low input capacitance (C_{iss})
- Reduced switching and conduction losses
- Ultra low gate charge (Qg)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
- Welding
- Induction heating
- Motor drives
- Battery chargers
- Renewable energy
- Solar (PV inverters)

ORDERING INFORMATION			
Package	DPAK (TO-252)		
Lead (Pb)-free and halogen-free	SiHD2N80E-GE3		

ABSOLUTE MAXIMUM RATINGS (T _C	= 25 °C, unle	ss otherwis	se noted)		
PARAMETER			SYMBOL	LIMIT	UNIT
Drain-source voltage			V _{DS}	800	v
Gate-source voltage			V _{GS}	± 30	- V
Continuous drain current (T _J = 150 °C)	V at 10 V	T _C = 25 °C T _C = 100 °C	°C I _D	2.8	
	V _{GS} at 10 V	T _C = 100 °C		1.8	А
Pulsed drain current ^a			I _{DM}	5	1
Linear derating factor				0.5	W/°C
Single pulse avalanche energy ^b			E _{AS}	14	mJ
Maximum power dissipation			PD	62.5	W
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +150	°C	
Drain-source voltage slope	T _J = 125 °C		d\//dt	70	1//22
Reverse diode dV/dt ^d			dV/dt	0.13	V/ns
Soldering recommendations (peak temperature) ^c	c For 10 s			300	°C

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature

b. V_{DD} = 140 V, starting T_J = 25 °C, L = 28.2 mH, R_g = 25 $\Omega,\,I_{AS}$ = 0.9 A

c. 1.6 mm from case

d. $I_{SD} \leq I_D, \, dI/dt$ = 100 A/µs, starting T_J = 25 $^\circ C$

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COMPLIANT

HALOGEN

FREE

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THERMAL RESISTANCE RATINGS								
PARAMETER	SYMBOL	TYP.		MAX.			UNIT	
Maximum junction-to-ambient	R _{thJA}	- 62						
Maximum junction-to-case (drain)	R _{thJC}	- 2.0				°C/W		
SPECIFICATIONS ($T_J = 25 \ ^{\circ}C$, u	SPECIFICATIONS (T _J = 25 °C, unless otherwise noted)							
PARAMETER	SYMBOL	TES	T CONDIT	IONS	MIN.	TYP.	MAX.	UNIT
Static								
Drain-source breakdown voltage	V _{DS}	V _{GS} =	= 0 V, I _D = 2	250 µA	800	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference	e to 25 °C,	I _D = 1 mA	-	1.0	-	V/°C
Gate-source threshold Voltage (N)	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D =	250 μA	2.0	-	4.0	V
			$V_{GS} = \pm 20$) V	-	-	± 100	nA
Gate-source leakage	I _{GSS}		$V_{GS} = \pm 30$) V	-	-	± 1	μA
7		V _{DS} =	= 800 V, V _C	_{3S} = 0 V	-	-	1	
Zero gate voltage drain current	IDSS	V _{DS} = 640 V	/, V _{GS} = 0 V	V, T _J = 125 °C	-	-	10	μA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	I	_D = 1.0 A	-	2.38	2.75	Ω
Forward transconductance	9 _{fs}	V _{DS}	= 30 V, I _D :	= 1.0 A	-	1.0	-	S
Dynamic	•					•		1
Input capacitance	C _{iss}		V _{GS} = 0 \	1	-	315	-	
Output capacitance	C _{oss}		$V_{GS} = 0.0$, $V_{DS} = 100$ V,		-	20	-	
Reverse transfer capacitance	C _{rss}	f = 1 MHz		-	6	-	-	
Effective output capacitance, energy related ^a	C _{o(er)}	$V_{DS} = 0$ V to 480 V, $V_{GS} = 0$ V		-	13	-	pF	
Effective output capacitance, time related ^b	C _{o(tr)}			-	45	-	1	
Total gate charge	Qg				-	9.8	19.6	
Gate-source charge	Q _{gs}	V _{GS} = 10 V	I _D = 1.0	A, V _{DS} = 480 V	-	2.4	-	nC
Gate-drain charge	Q _{gd}				-	3.9	-	1
Turn-on delay time	t _{d(on)}				-	11	22	
Rise time	t _r	- 	- 480 V I-	- 1 O A	-	7	14	
Turn-off delay time	t _{d(off)}	VDD - V _{GS} =	$V_{DD} = 480 \text{ V}, \text{ I}_D = 1.0 \text{ A}, V_{GS} = 10 \text{ V}, \text{ R}_g = 9.1 \Omega$		-	19	38	ns
Fall time	t _f				-	27	54	
Gate input resistance	Rg	f = 1	MHz, ope	n drain	1.8	3.6	7.2	Ω
Drain-Source Body Diode Characteristi	cs							
Continuous source-drain diode current	١ _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	2.8		
Pulsed diode forward current	I _{SM}			-	-	5	A	
Diode forward voltage	V _{SD}	T _J = 25 °C, I _S = 1 A, V _{GS} = 0 V		-	-	1.2	V	
Reverse recovery time	t _{rr}				-	278	556	ns
Reverse recovery charge	Q _{rr}	$T_J = 25 \text{ °C}, I_F = I_S = 1.0 \text{ A},$ dl/dt = 100 A/µs, V _R = 25 V		-	0.9	1.8	μC	
Reverse recovery current	I _{RRM}			-	5	-	A	

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}

b. Coss(tr) is a fixed capacitance that gives the same charging time as Coss while VDS is rising from 0 % to 80 % VDSS

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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

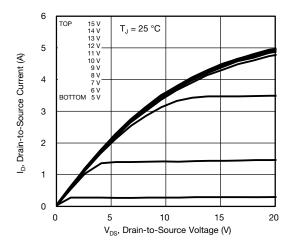
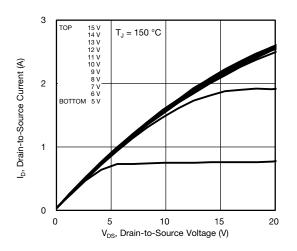
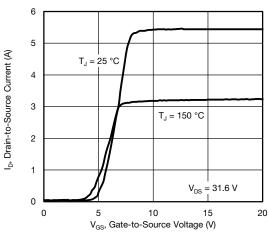


Fig. 1 - Typical Output Characteristics









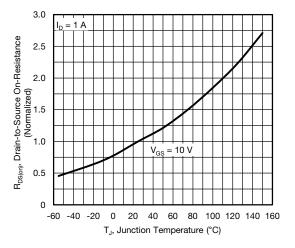


Fig. 4 - Normalized On-Resistance vs. Temperature

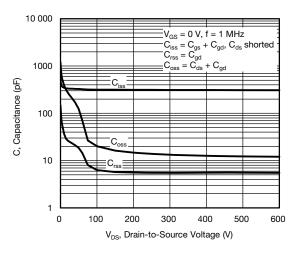


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

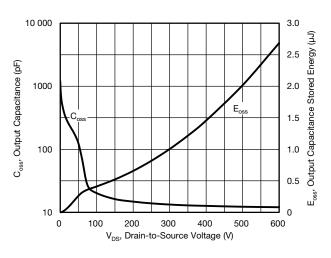


Fig. 6 - C_{oss} and E_{oss} vs. V_{DS}

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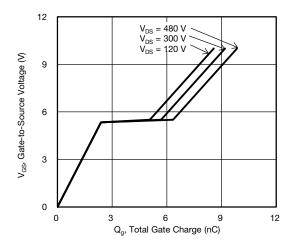


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

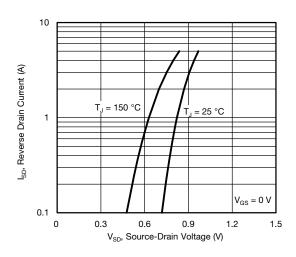


Fig. 8 - Typical Source-Drain Diode Forward Voltage

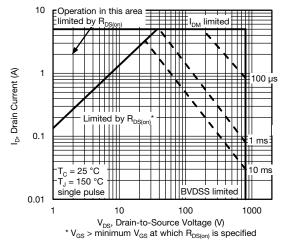


Fig. 9 - Maximum Safe Operating Area

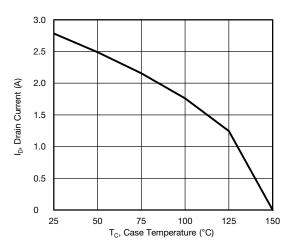


Fig. 10 - Maximum Drain Current vs. Case Temperature

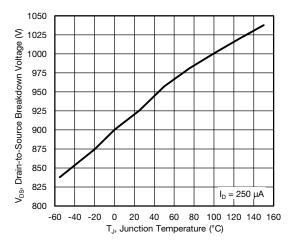


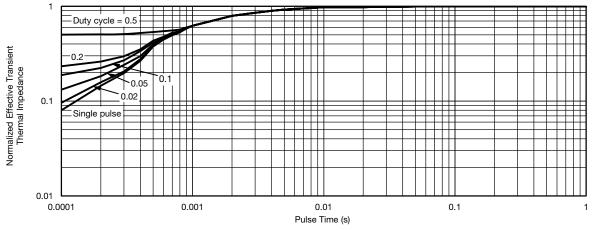
Fig. 11 - Temperature vs. Drain-to-Source Voltage

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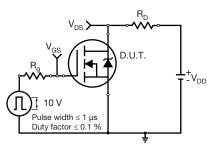


Fig. 13 - Switching Time Test Circuit

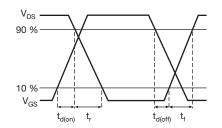


Fig. 14 - Switching Time Waveforms

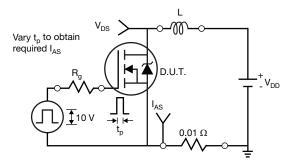


Fig. 15 - Unclamped Inductive Test Circuit

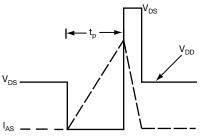


Fig. 16 - Unclamped Inductive Waveforms

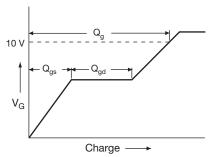


Fig. 17 - Basic Gate Charge Waveform

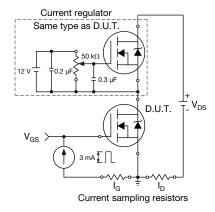


Fig. 18 - Gate Charge Test Circuit

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Peak Diode Recovery dV/dt Test Circuit

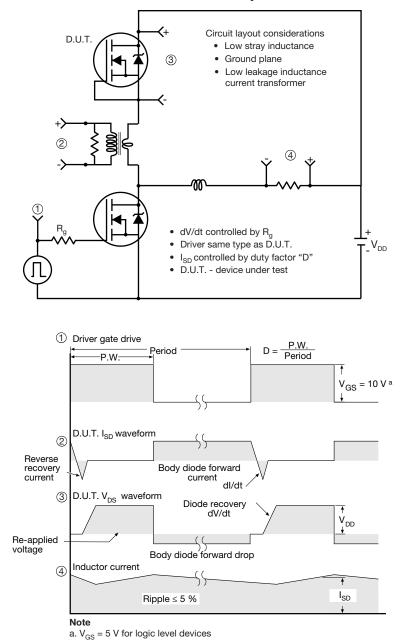


Fig. 19 - For N-Channel

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TO-252AA Case Outline

VERSION 1: FACILITY CODE = Y







	MILLIMETERS		
DIM.	MIN.	MAX.	
А	2.18	2.38	
A1	-	0.127	
b	0.64	0.88	
b2	0.76	1.14	
b3	4.95	5.46	
С	0.46	0.61	
C2	0.46	0.89	
D	5.97	6.22	
D1	4.10	-	
E	6.35	6.73	
E1	4.32	-	
Н	9.40	10.41	
е	2.28 BSC		
e1	4.56 BSC		
L	1.40	1.78	
L3	0.89	1.27	
L4	-	1.02	
L5	1.01	1.52	

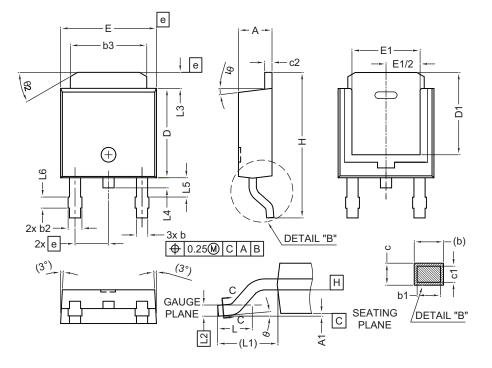
Note

• Dimension L3 is for reference only



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VERSION 2: FACILITY CODE = N



	MILLIMETERS		
DIM.	MIN.	MAX.	
A	2.18	2.39	
A1	-	0.13	
b	0.65	0.89	
b1	0.64	0.79	
b2	0.76	1.13	
b3	4.95	5.46	
С	0.46	0.61	
c1	0.41	0.56	
c2	0.46	0.60	
D	5.97	6.22	
D1	5.21	-	
E	6.35	6.73	
E1	4.32	-	
e	2.29 BSC		
Н	9.94 10.34		

	MILLIMETERS		
DIM.	MIN.	MAX.	
L	1.50	1.78	
L1	2.74 ref.		
L2	0.51 BSC		
L3	0.89	1.27	
L4	-	1.02	
L5	1.14	1.49	
L6	0.65	0.85	
θ	0°	10°	
θ1	0°	15°	
θ2	25°	35°	

Notes

• Dimensioning and tolerance confirm to ASME Y14.5M-1994

• All dimensions are in millimeters. Angles are in degrees

• Heat sink side flash is max. 0.8 mm

Radius on terminal is optional

ECN: E19-0649-Rev. Q, 16-Dec-2019 DWG: 5347



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RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)



Recommended Minimum Pads Dimensions in Inches/(mm)

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